Description

The FS2012 mass flow sensor module measures the flow across a sensing surface using the thermo-transfer (calorimetric) principle. The FS2012 is capable of measuring gas or liquid medium.

The FS2012 offers key advantages over other flow solutions. The sensor utilizes series of MEMS thermocouples, which provide excellent signal-to-noise ratio. The solid thermal isolation along with the silicon-carbide film coating offers excellent abrasive wear resistance and long-term reliability.

The high temperature material used in the flow channel housing and base allows for a wide operating temperature.

Wetted materials consist of a proprietary modified PPO plastic, epoxy, and silicon carbide.

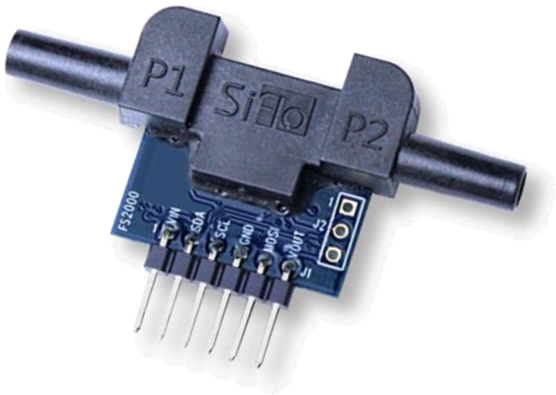
Typical Applications

- Process controls and monitoring
- Oil and gas leak detection
- HVAC and air control systems
- CPAP and respiratory devices
- Automotive MAF
- Liquid dispensing systems

Features

- Gas or liquid mediums
- Robust solid isolation technology
- Resistant to surface contamination
- No cavity to cause clogging
- Resistant to vibration and pressure shock
- Low-power application
- High-temperature flow housing
- Low signal-to-noise ratio
- Analog output: 0V to 5V
- Digital output: I²C
- Supply voltage: 5V
- Module operating temperature range: 0°C to +85°C
- 53.35 x 24.0 mm module with 6-pin header

FS2012 Flow Sensor Module



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